

S/N 09/382,524

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Unknown

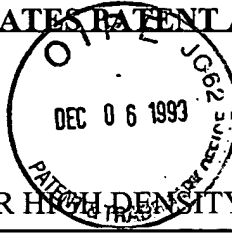
Serial No.: 09/382,524

Group Art Unit: 2812

Filed: August 25, 1999

Docket: 303.610US1

Title: INSULATORS FOR HIGH DENSITY CIRCUITS



COMMUNICATION CONCERNING CO-PENDING APPLICATION(S)

Assistant Commissioner for Patents
Washington, D.C. 20231

Applicant would like to bring to the Examiner's attention the following related co-pending application(s) in the above-identified patent application:

Serial No.	Filing Date	Title
08/892,114	07/14/1997	Method of Forming Insulating Material for an Integrated Circuit and Integrated Circuits Resulting from Same

Respectfully submitted,

PAUL A. FARRAR

By Applicant's Representatives,

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Date November 30, 1999

By Danny J. Radys

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231 on November 30, 1999.

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